

Heppla® H7200 TC32 EC

Material Description:

Heppla® H7200 TC32 EC is a unreinforced Polyamide 66 product.Characteristics include:Thermally Conductive, Electrically Conductive.

General	
Material Status	<ul style="list-style-type: none"> Commercial: Active
Availability	<ul style="list-style-type: none"> Asia Pacific Europe Middle East North America Latin America Africa
Features	<ul style="list-style-type: none"> Electrically Conductive Wear Resistant Heat Resistant Thermally Conductive Weather Resistant
RoHS Compliance	<ul style="list-style-type: none"> Contact Manufacturer
Processing Method	<ul style="list-style-type: none"> Injection Molding

Physical Properties	Typical Value	Unit	Test Method
Specific Gravity	1.71	g/cm ³	ASTM D792
Moisture Content	0.2	%	

Mechanical Properties	Typical Value	Unit	Test Method
Tensile Modulus	18305	MPa	ASTM D638
Tensile Strength	35.3	MPa	ASTM D638
Tensile Elongation(Yield)	< 1	%	ASTM D638
Flexural Modulus	17507	MPa	ASTM D790
Flexural Strength	76.4	MPa	ASTM D790

Impact Properties	Typical Value	Unit	Test Method
Notched Izod Impact (3.2mm)	26.5	J/m	ASTM D256
Unnotched Izod Impact (3.2mm)	79.1	J/m	ASTM D4812

Electrical Properties	Typical Value	Unit	Test Method
Volume Resistivity	< 1.0E+2	Ohms-cm	ASTM D257
Surface Resistivity	< 1.0E+4	Ohm/sq	ASTM D257

Thermal Properties	Typical Value	Unit	Test Method
Thermal Conductivity			
Through-plane	6.3	W/(m.K)	ASTM E1530
In-plane	32	W/(m.K)	ASTM E1461-92

Processing Information	Typical Value	Unit
Injection Pressure	70 to 125	MPa
Melt Temperature	275 to 301	°C
Mold Temperature	65 to 108	°C
Drying Temperature	79	°C
Drying Time	4	hr
Dew Point	-18	°C

CAUTION/警告!

Before using, read the Molding Guide, Material Safety Data Sheets, and Bulletins available from NFD Advanced Composites Sales offices and Distributors supplied to your company. Caution! During drying, purging and molding, small amounts of hazardous gases and/or particulate matter may be released. These may irritate eyes, nose and throat. Use adequate local exhaust ventilation during thermal processing. To prevent resin decomposition, do not contaminate the resin or exceed the recommended melt temperature or hold-up time. Avoid inhalation or skin and eyes contact. Sweep up and dispose of spilled resin to eliminate slipping hazard. 在使用之前, 请阅读NFD公司销售办事处和经销商提供给贵公司的材料成型指南、材料安全数据表和公告。警告! 在干燥、吹扫和成型过程中, 少量有害气体或颗粒物质可能会在被释放, 这些可能会刺激眼睛, 鼻子和喉咙。热处理过程中请注意做好排气通风工作。为防止树脂分解, 请勿污染树脂或超过我们为您推荐

LEGAL NOTICES/法律声明

The figures indicated here are approximate values. They may be affected by different factors, and the user is not released therefore from the obligation of performing checks and trials of his own. The values indicated here have been compiled on the basis of current tests and findings. Any legally binding guarantee of certain properties, or any suitability for a specific application can not be inferred from the present data. For detailed production regulatory information, contact customer service.

上列数据只作参考用途, 它们可能会受不同因素的影响, 使用者有责任通过实验自行确定材料特性。上述资料根据现有测试得出, 对物料特性是否适合某特殊用途及特性不能给予保证, 数据也没有任何法律约束力。更多有关详细的产品监管信息, 请联系客户服务

COMPANY/公司:

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感谢您访问新孚达 (NFD)! 我们秉承 "New Formula Designer" 的发展理念, 将科研创新与生产应用紧密相连, 无论您是设计师、工程师或者是采购专家, 我们都可以帮助您拓展业务并获得新的灵感。我们坚持诚信、合作、效率、创新的核心价值观, 始终把客户放在第一位。相比于我们的竞争对手, 我们专注于为您提供更先进的技术配方、更优质的产品, 更好的解决方案及更周到的售后服务, 我们懂市场、我们懂产品、我们更懂你们。

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